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JC/900

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10064500	FILING DATE 07/22/2002	CLASS 219	SUBCLASS 678, 000	GAU 3742	EXAMINER Van
** APPLICANTS: Barmatz Martin; Mai John; Jackson Henry; Budraa Nasser; Pike William; 678, 000					
** CONTINUING DATA VERIFIED: No					
** FOREIGN APPLICATIONS VERIFIED: No					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO			
35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		06618/891001 / CIT 2969 C			
Verified and Acknowledged Examiners's initials <i>JC</i>					
TITLE : Microwave bonding of thin film metal coated substrates					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims 35	Print Claim for O.G. 1
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg. 3	Figs. Drwg. 7
		Print Fig. 1	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner JC	
		PREPARED FOR ISSUE	
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